NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration TO-46.
EXAMPLE BOARD LAYOUT

NDV0003H

TO-CAN - 2.67 mm max height

TO-46

LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 12X
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